

Nanomechanical Property Characterization of Adhesive Bondlines

Rita Olander, PhD Candidate MSE

PI: Brian Flinn

Research Collaboration FAA, Boeing, and UW FAA Tech Monitor: Ahmet Oztekin FAA Sponsors: Cindy Ashforth, Larry Ilcewicz



Outline





Motivation & Key Considerations Long-Term Exposure Effects

- Composite joints are designed to undergo thousands of service hours under environmental conditions (e.g. hot-wet, fuel, hydraulic fluid)
 - Diffusion of moisture Æhygrothermal effects _
 - Cyclic loading Æratchet and fatigue effects —
 - Oxygen-rich and elevated temperatures Æthermo-oxidative effects
- Better techniques for evaluating long-term exposure on bondline interphase and constituents are desired
 - Physical and chemical changes —
 - Changes in mass density and toughness
 - Plasticize
 - Tg changes
 - Moisture absorption, cross-link density, free volume

 $\frac{3}{4}$ Do regions within the bondline behave differently long-term?

 $\frac{3}{4}$ Are bonds changing, and if so, are they changing at different rates?





Olander. R., 3

Composite Bond Architecture Types





Motivation & Key Considerations

- Bonding creates an interphase between two materials
 - Interphase can affect bond strength and durability
 - factors influencing interphase development need further investigation
- Characterization of the micron-scale regions within bondlines is complex due to their size
 - Complex microstructures and chemistries different from bulk materials
 - Investigate effect of potential changes in microconstituents









Preliminary Investigation

- Nanomechanical method to evaluate adhesive bondlines was developed
- Distinct bondline regions were detected



• Properties in distinct bondline regions were found to be statistically different





Value to Industry

- Support evaluation of existing or new bonding systems
 - Characterize interfaces and/or interphases within systems
 - Bulk properties vs. Interface/Interphase proprieties
 - Evaluate effect of toughening particles, scrim, additives, etc.
 - Potentially act as screening tests for new systems
 - Process development
- Further understand the long-term exposure effects
 - C01 (har)-3 (ac)-1 M (y)-1 ()93.6f2 (s)-10 (oc)-.6 mel-1 (s)-5 rsPot5acemts









- 2. Development of model system to investigate degree of comingling
 - Controlled mixtures of bulk adhesive and bulk resin
 - "Cocure Interphase Mixtures" based on "Rule of Mixtures" Theory









- 2. Development of model system to investigate degree of comingling
 - Controlled mixtures of bulk adhesive and bulk resin
 - "Cocure Interphase Mixtures" based on "Rule of Mixtures" Theory

Model #	Fabrication Method	Adherend Resin	Adhesive Resin
1	Acetone Extraction	Toray T800S/3900-2 Prepreg	Solvay Metlbond® 1515-3 modified epoxy supported
2	"Neat" Resin, FlackTek SpeedMixer®	Toray 3900-2 Same Qualified Resin Transfer Molding (SQTRM)	AF 555 unsupported film







3. Investigation of high temperature exposure effects on interphases in bondlines

		Surface Preparation		
	Bond Type	Adherend ^[F1]	(cured adherend only) [F2]	Adhesive [F3]
Baseline	Secondary Bond	Toray T800S/3900 resin	Diatex 1500EV6 woven polyester	Solvay Metlbond® 1515-4
DCB Sample ^[F4]			peel ply	modified epoxy supported
Baseline	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
DCB Sample ^[F5]			polyester peel ply	modified epoxy supported
2hrs @ 330 qF	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
DCB Sample ^[F5]			polyester peel ply	modified epoxy supported
1hr @ 400 qF	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
DCB Sample ^[F5]			polyester peel ply	modified epoxy supported
30days @ 3300 qF	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
DCB Sample ^[F5]			polvester peel plv	modified epoxy supported
Lab Ambient 2008 Exposure DCB	Secondary Bond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
Sample ^[F5]			polyester peel ply	modified epoxy supported
2012 environmentally exposed	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
Scrapped Cobond ^[F4, F6]		Toray FGF-108 29M	polyester peel ply	modified epoxy supported
Scrapped Parts Cobond ^[F4, F6]	Cobond	Toray T800S/3900 resin	Precision Fabric Group 60001	Solvay Metlbond® 1515-3
	Time, 5	Toray FGF-108 29M	polyester peel ply	modified epoxy supported

[F1] 350°F cured carbon fiber reinforced polymer matrix

[F2] Peel ply removed just prior to bonding

[F3] 350°F cured film adhesive

[F4] Samples produced by manufacturer

[F5] Samples produced by UW in lab setting

[F6] boneyard uncontrolled environment not maintained and exposed to the elements (e.g., standing water)





Coupon Considerations

Bondline variation observed through nanomechanical testing could be due to:

• Different material batchesine variation re Wn BT 0 scn /TT0 1 Tf 1





6/14/2024

Nanomechanical and Nanochemical Anaylsis

Olander, R., 16 ritaj2@uw.edu

Nanoindentation Methodology

- Hysitron TriboIndenter 980 with Berkovich diamond indenter tip
- Indent surface from tens of nanometers to several micrometers deep
- Extreme Property Mapping (XPM[™])
 - Hardness and reduced modulus mapped across bondline
- Nano-Dynamic Mechanical Analysis (NanoDMA)





Hysitron TriboIndenter 980 at U. Washington



ritaj2@uw.edu

Nanoindentation Limitations

- At this time, no relationship exists between nanomechanical characterization to any engineering properties used in the design, analysis and certification of bonded composite structures
- Subsurface heterogeneity can influence measurements
- Plastic zone around indentation can affect nearby measurements
 - Increasing spacing can prevent plastic zone interactions but results in lower spatial resolution







Nanomechanical Characterization

• Nanodynamic mechanical analysis on a submicron scale ÆOscillating force applied to nanoindenter tip Æsinusoidal stress is applied Æstrain of the material is measured ÆMeasures viscoelastic properties of the material $Tan(delta) = \frac{E^{\tilde{n}\,\tilde{n}}}{E^{\tilde{n}}}$





Nanochemical Characterization

Photo-induced Force Microscopy (PiFM)

- Non-contact AFM method relying on tipsample force interactions [19,20]
- Highly localized field created by excitation laser focused on a metal coated AFM tip [19,20]
- Fixed-wavelength PiF images -3 (h scn (x)Qn)]TJ 0.103 Tw-99.0 -0.96 Td [id iial c
 - nti-1 (f)-3 bycacteri-1 scti oriosycii-3 (h s)]TJ 0.003 Tw 0 -0.9 am(er)-3 (at)-.r]





6/14/2024

Preliminary Results

Olander, R., 22 ritaj2@uw.edu

Bondline Property Mapping

XPM – Cobond Toray 3900-2 and Solvay MB1515-3



Cobonded systems show distinctive mechanical property trend within bondline:

Resin> Cocure Interphase > "Bulk" Adhesive > Adhesive near Secondary Bond Interphase











NanoDMA Cobond Toray 3900-2 and Solvay MB1515-3



Preliminary Conclusions

- Cobonded Systems have distinctive nanomechanical properties
 - Cobonded interphase regions showed intermediate values between the "bulk" properties of the adhesive and resin Æsignificant mixing during cure
 - Nanomechanical property trend within bondline

Resin Cocure Interphase "Bulk" Adhesive Adhesive near Secondary Bond Interphase

- Nanomechanical properties change with high temperature exposures
 - Increase in modulus and hardness suggest "post cure" effect after high temp exposure below T_q
 - Decrease in modulus potentially indicating change of materials after high temp exposure <u>above</u> T_g
 - NanoDMA may be able to detect subtle changes in T_g due to the degree of comingling across bondline regions in cobonded systems





On-going Work

- 1. Nanochemical Analyis PiFM on bonded systems
- 2. "Cocure Interphase Mixtures" Model System
 - Characterization of comingling regions using controlled mixtures
 - T_g
 - Chemical Analysis
- 3. Characterize adhesive bondlines with various heat exposures
 - Correlate adhesive bondlines with various exposures to controlled mixtures Æ understand the effect of heat exposures on bondline properties





On-going Work

- 1. Nanochemical Analyis PiFM
- PiF spectra indicates peak location shifts, broadening/sharpening, absorbance
 - Peak 1 shift with increased comingling
 - Peak 2 peak broadening with increased comingling

PiFM can be used to estimate the degree of comingling in each bondline region





Olander, R., 30 RROI# 24-181587-ETT



Acknowledgements

- University of Washington
 Molecular Analysis Facility, National Science Foundation (grant NNCI-15.







